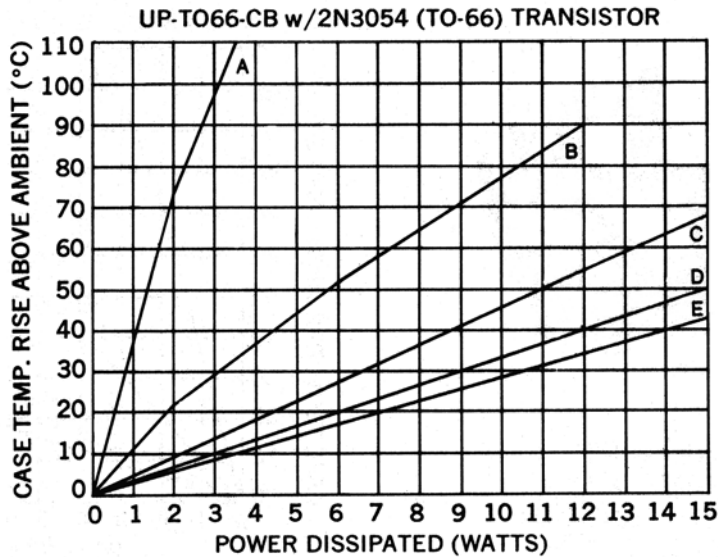
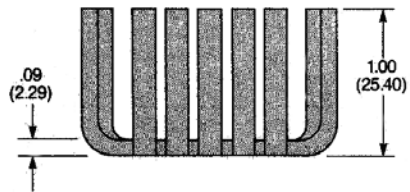
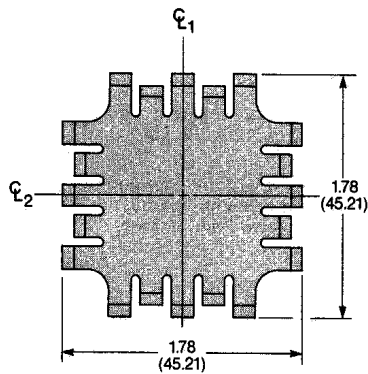


METAL CASE, CASE-MOUNTED SEMICONDUCTORS

UP Series for TO-66 Outline

Natural Conv. ($^{\circ}\text{C}/\text{W}$): 7.1
 Forced Air ($^{\circ}\text{C}/\text{W}$): 2.5
 Mounting Envelope: 1.78" x 1.78" x 1.00"



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

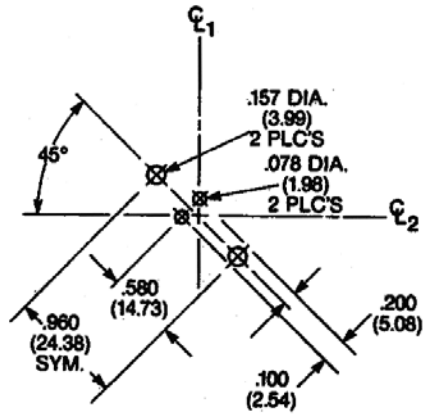
- Thermal Resistance Case to Sink is 0.5-0.7 $^{\circ}\text{C}/\text{W}$ w/Joint Compound.
- Derate 0.8 $^{\circ}\text{C}/\text{watt}$ for unplated part in natural convection only.

Ordering Information

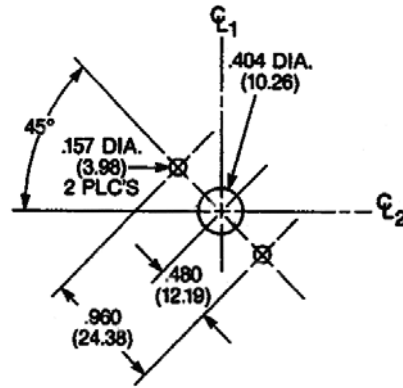
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
UP-TO66-U	UP-TO66-CB	UP-T66-B	TO-66	24	22.5
UP-TO66-47U	UP-TO66-47CB	UP-TO66-47B	TO-66 IC	25	22.5
UP-TO66-52U	UP-TO66-52CB	UP-TO66-52B	TO-66 IC (Socket)	26	22.5

HOLE PATTERNS

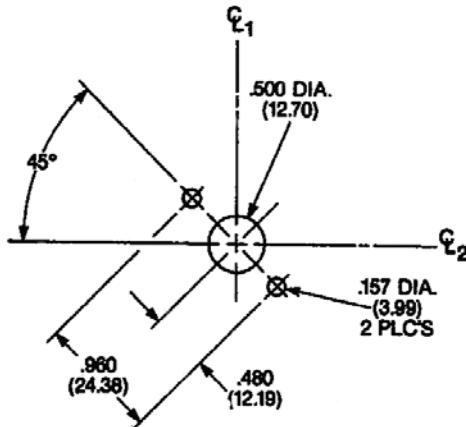
24. Hole pattern no. 114 accommodates TO-66s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



25. Hole pattern no. 199 accommodates TO-66 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



26. Hole pattern no. 226 accommodates TO-66 ICs (socket). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



CTS IERC, Heat Sinks and Thermal Management Solutions

413 North Moss Street, Burbank, California 91502 Tel: (818) 842-7277 Fax: (818) 848-8872